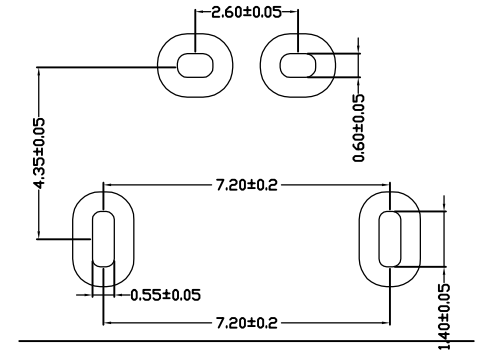
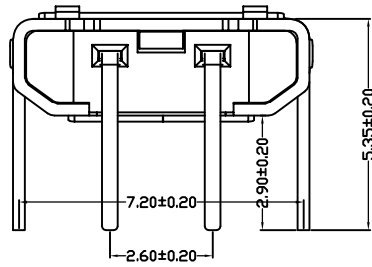
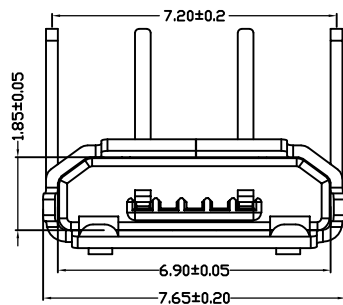
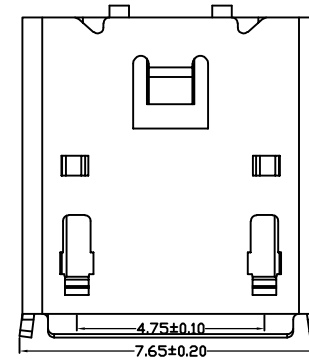
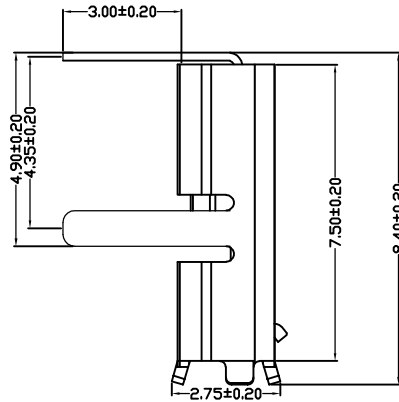
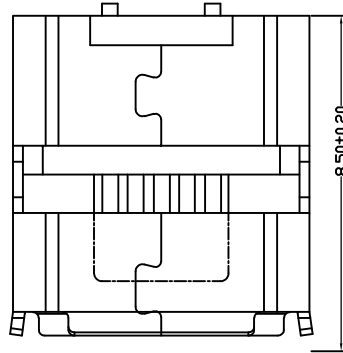


修改序号	修改说明	签名	日期
A/0			



PCB LAYOUT



Note:

1. Material:

- 1.1 Housing: High temperature thermoplastic with g.f, UL94v-0
- 1.2 Contact: copper alloy, t=0.20mm
- 1.3 Shell: SPCC t=0.3mm or SUS t=0.25

2. Specification:

- 2.1 Current rating: 1A Max
- 2.2 Dielectric withstanding voltage: 100V(AC) for 1 min.
- 2.3 Contact resistance: 40mΩ Max.
- 2.4 Insulation resistance: 100MΩ min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min. 0.81~2.05 Kgf Min. after 1500 or 10,000 insertion/extraction cycles
- 2.7 Temperature range: -30° C~80° C

尺寸	允许公差
.X	±0.50
.X	±0.20
.XX	±0.10
.XXX	±0.03
角度	±1.00°

深圳市创勤科技有限公司 Shenzhen Chuangqin Technology Co., Ltd.			
图纸类型		图纸名称:	
产品工程图		MICRO USB BF 2P DIP7. 2(3.0*0.9)插板	
设计	LIN YUN	2011.07.21	产品料号
审核			CQ028-MFLT20301001
视图			版号: A/0